Multilayer Fan-out Packaging

Purpose	With a combination innovative optical design plus advanced inspection algorithm, STI offers various inspection & handling solutions to address stringent wafer level fan-out packaging requirements.
Technology	1. **On-the-Fly Dual Image Capture** – Captures two images using two independent illuminations. Enables capturing challenging multilayer features like RDL, Kerf, Overlay, Land Pads, Bumps and Top surface simultaneously without compromising throughput and inspection resolution. 2. **Dicing Defect Metrology** – Field proven inspection algorithm to inspect Edge & Corner Defects, Active Die, Saw Street Quality, Die Alignment on Stretched wafer, Die Edge Micro Crack Inspection, Die Shift Inspection and Overlay 3. **OTF Confocal 3D** – 3D metrology for high density micro bumps, Cu pillars, RDL and 4. **OTF Triangulation 3D** – Designed for high volume, high speed 3D Metrology solutions for Post Dicing, Assembly & Post Test requirements.

STI Products	On-the-Fly Dual Image Capture	Dicing Defect Metrology	OTF Confocal 3D	OTF Triangulation 3D
iFocus – Wafer 2D & 3D Scan	✓	✓	✓	
Hexa – Tray 2D & 3D Scan				✓
tSort - WLP Scan & Sort		✓		